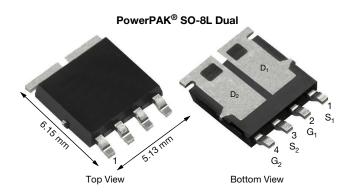


Vishay Siliconix

# Automotive Dual N-Channel 60 V (D-S) 175 °C MOSFET



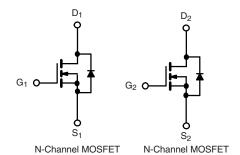
PRODUCT SUMMARY	
V <sub>DS</sub> (V)	60
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 10 \text{ V}$	0.020
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 4.5 \text{ V}$	0.024
I <sub>D</sub> (A) per leg	23
Configuration	Dual

#### **FEATURES**

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>q</sub> and UIS tested
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912







ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SQJ952EP-T1 (for detailed order number please see <a href="https://www.vishay.com/doc?79771">www.vishay.com/doc?79771</a> )

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V <sub>DS</sub>	60	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C	1	23		
Continuous Drain Current	T <sub>C</sub> = 125 °C	I <sub>D</sub>	13		
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	23	Α	
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	93		
Single Pulse Avalanche Current		I <sub>AS</sub>	21		
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	22	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	Б	25	W	
	T <sub>C</sub> = 125 °C	$P_{D}$	8.3		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Soldering Recommendations (Peak Temperature) c, d			260	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount c	$R_{thJA}$	85	°C/W
Junction-to-Case (Drain)		$R_{thJC}$	6	C/VV

#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %
- b. When mounted on 1" square PCB (FR4 material)
- c. See solder profile (<a href="www.vishay.com/doc?73257">www.vishay.com/doc?73257</a>). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection



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d. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> :	= 0 V, I <sub>D</sub> = 250 μA	60	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.5	2.0	2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V	-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C	-	-	150	
On-State Drain Current a	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 \text{ V}$	30	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10.3 A	-	0.012	0.020	
Drain-Source On-State Resistance a	В	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10.3 A, T <sub>J</sub> = 125 °C	-	-	0.030	0
Drain-Source On-State Resistance 4	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> =10.3 A, T <sub>J</sub> = 175 °C	-	-	0.040	Ω
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 10.3 A	-	0.016	0.024	
Forward Transconductance b	9 <sub>fs</sub>	V <sub>DS</sub> =	= 15 V, I <sub>D</sub> = 10.3 A	-	68	-	S
Dynamic <sup>b</sup>							•
Input Capacitance	C <sub>iss</sub>			-	1500	1800	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{DS} = 30 \text{ V}, f = 1 \text{ MHz}$	-	130	156	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	55	66	
Total Gate Charge <sup>c</sup>	Qg			-	24	30	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 30 \text{ V}, I_D = 4.5 \text{ A}$	-	5	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	12	=.	
Gate Resistance	Rg		f = 1 MHz	0.6	1.3	2.6	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	9	12	
Rise Time <sup>c</sup>	t <sub>r</sub>	V <sub>DD</sub> :	= 30 V, $R_L = 30 \Omega$	-	6	8	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 1 \text{ A}, Y$	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	25	30	ns
Fall Time <sup>c</sup>	t <sub>f</sub>			-	9	12	
Source-Drain Diode Ratings and Chara	acteristics b						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	93	Α
Forward Voltage	$V_{SD}$	$I_{\rm F} = 10.3  \text{A},  \text{V}_{\rm GS} = 0  \text{V}$ - 0.7		0.7	1.1	V	

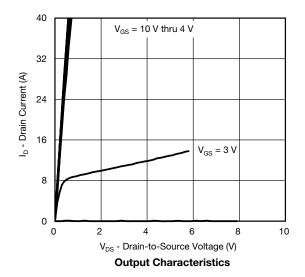
### Notes

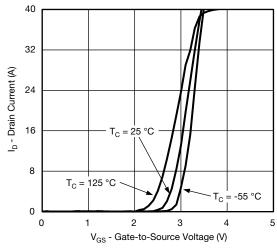
- e. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- f. Guaranteed by design, not subject to production testing.
- g. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

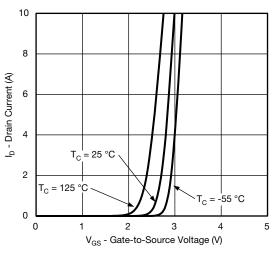


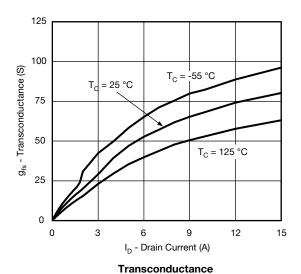
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



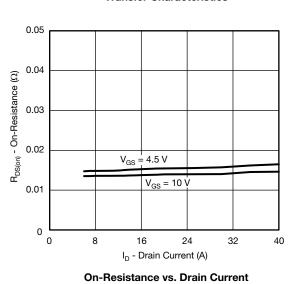


#### **Transfer Characteristics**





### **Transfer Characteristics**

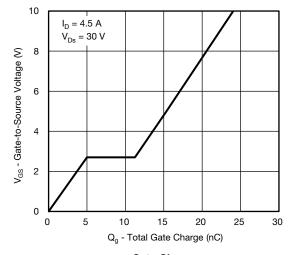


2000 1600 C<sub>iss</sub> 1200 400 400 0 10 20 30 40 50 60

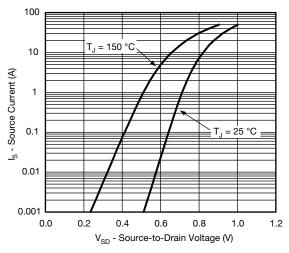
 $V_{DS}$  - Drain-to-Source Voltage (V) **Capacitance** 



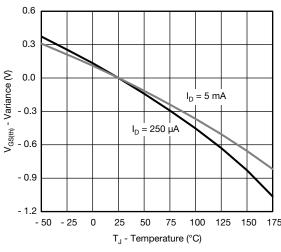
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



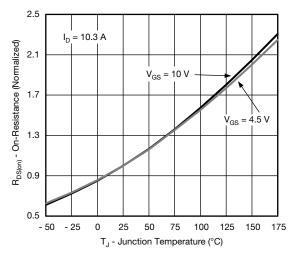
#### **Gate Charge**



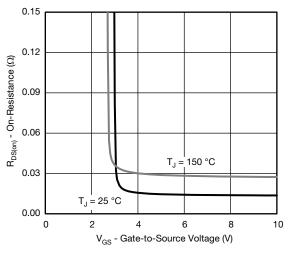
**Source Drain Diode Forward Voltage** 



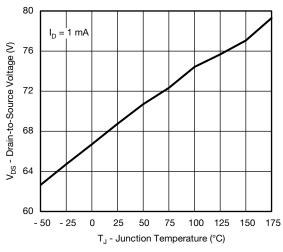
**Threshold Voltage** 



On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage

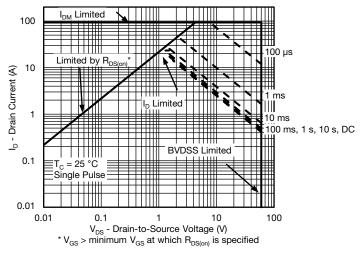


Drain Source Breakdown vs. Junction Temperature

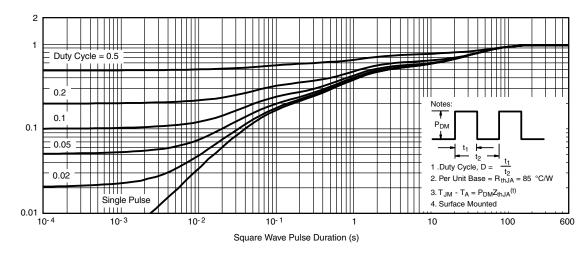


Normalized Effective Transient Thermal Impedance

## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



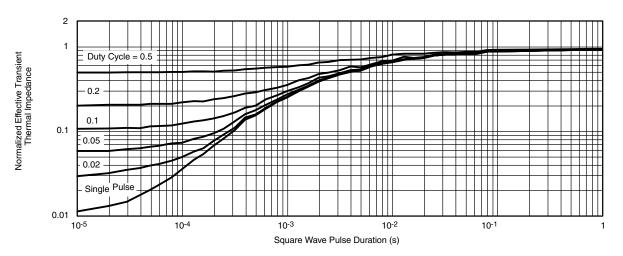
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



### THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?62862.



# PowerPAK® SO-8L Case Outline 2



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DIM		MILLIMETERS		INCHES				
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX		
Α	1.00	1.07	1.14	0.039	0.042	0.045		
A1	0.00	-	0.127	0.00	-	0.005		
b	0.33	0.41	0.48	0.013	0.016	0.019		
b1	0.44	0.51	0.58	0.017	0.020	0.023		
b2	4.80	4.90	5.00	0.189	0.193	0.197		
b3		0.094		0.004				
b4		0.47			0.019			
С	0.20	0.25	0.30	0.008	0.010	0.012		
D	5.00	5.13	5.25	0.197	0.202	0.207		
D1	4.80	4.90	5.00	0.189	0.193	0.197		
D2	3.86	3.96	4.06	0.152	0.156	0.160		
D3	1.63	1.73	1.83	0.064	0.068	0.072		
е		1.27 BSC			0.050 BSC			
Е	6.05	6.15	6.25	0.238	0.242	0.246		
E1	4.27	4.37	4.47	0.168	0.172	0.176		
E2	2.75	2.85	2.95	0.108	0.112	0.116		
E3	6.05	6.22	6.40	0.238	0.245	0.252		
F	-	-	0.15	-	-	0.006		
L	0.62	0.72	0.82	0.024	0.028	0.032		
L1	0.92	1.07	1.22	0.036	0.042	0.048		
K		0.51			0.020			
W		0.23			0.009			
W1		0.41			0.016			
W2	2.82			0.111				
W3		2.96			0.117			
θ	0°	-	10°	0°	-	10°		

DWG: 6044

#### Note

• Millimeters will govern



### RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L DUAL



Recommended Minimum Pads Dimensions in mm (inches) Keep-out 6.75 (0.266) x 7.75 (0.305)



### RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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